Features

- Low-voltage and Standard-voltage Operation
 - $-2.7 (V_{CC} = 2.7V \text{ to } 5.5V)$
- Three-wire Serial Interface
- 2 MHz Clock Rate Compatibility
- Self-timed Write Cycle (10 ms max)
- High Reliability
 - Endurance: 1 Million Write Cycles
 - Data Retention: 100 Years
- Lead-free/Halogen-free Devices Available
- 8-lead JEDEC SOIC and 8-lead TSSOP Packages

Description

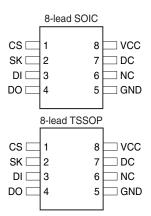
The AT93C46A provides 1024 bits of serial electrically-erasable programmable readonly memory (EEPROM) organized as 64 words of 16 bits each. The device is optimized for use in many automotive applications where low-power and low-voltage operation are essential. The AT93C46A is available in space-saving 8-lead JEDEC SOIC and 8-lead TSSOP packages.

The AT93C46A is enabled through the Chip Select pin (CS) and accessed via a three-wire serial interface consisting of Data Input (DI), Data Output (DO), and Shift Clock (SK). Upon receiving a Read instruction at DI, the address is decoded and the data is clocked out serially on the data output pin DO. The write cycle is completely self-timed and no separate erase cycle is required before write. The write cycle is only enabled when the part is in the erase/write enable state. When CS is brought high following the initiation of a write cycle, the DO pin outputs the ready/busy status of the part.

The AT93C46A is available in 2.7V to 5.5V versions.

Table 1. Pin Configuration

Pin Name	Function
CS	Chip Select
SK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
GND	Ground
VCC	Power Supply
NC	No Connect
DC	Don't Connect





Three-wire Automotive Temperature Serial EEPROM

1K (64 x 16)

AT93C46A





Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground1.0V to +7.0V
Maximum Operating Voltage 6.25V
DC Output Current 5.0 mA

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 1. Block Diagram

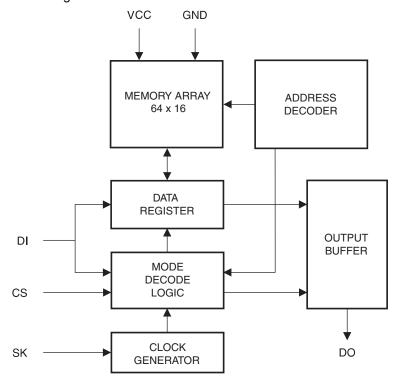


Table 2. Pin Capacitance

Applicable over recommended operating range from $T_A = 25$ °C, f = 1.0 MHz, $V_{CC} = +5.0$ V (unless otherwise noted)

Symbol	abol Test Conditions		Units	Conditions
C _{OUT}	Output Capacitance (DO)	5	pF	$V_{OUT} = 0V$
C _{IN}	Input Capacitance (CS, SK, DI)	5	pF	$V_{IN} = 0V$

Note: This parameter is characterized and is not 100% tested.

Table 3. DC Characteristics

Applicable over recommended operating range from: $T_A = -40$ °C to +125°C, $V_{CC} = +2.7V$ to +5.5V, (unless otherwise noted).

Symbol	Parameter	Test Condition		Min	Тур	Max	Unit
V _{CC1}	Supply Voltage			2.7		5.5	V
	Cumply Current	.,,	Read at 1.0 MHz		0.5	2.0	mA
I _{CC}	Supply Current	$V_{CC} = 5.0V$	Write at 1.0 MHz		0.5	2.0	mA
I _{SB1}	Standby Current	V _{CC} = 2.7V	CS = 0V		6.0	10.0	μΑ
I _{SB2}	Standby Current	V _{CC} = 5.0V	CS = 0V		10.0	15.0	μΑ
I _{IL}	Input Leakage	$V_{IN} = 0V \text{ to } V_{CC}$			0.1	3.0	μΑ
I _{OL}	Output Leakage	$V_{IN} = 0V \text{ to } V_{CC}$			0.1	3.0	μΑ
V _{IL1} ⁽¹⁾	Input Low Voltage	$2.7V \le V_{CC} \le 5.5V$		-0.6		0.8	V
V _{IH1} ⁽¹⁾	Input High Voltage	$2.7V \leq V_{CC} \leq 5.5V$		2.0		V _{CC} + 1	V
V _{OL1}	Output Low Voltage	$2.7V \leq V_{CC} \leq 5.5V$	I _{OL} = 2.1 mA			0.4	V
V _{OH1}	Output High Voltage	$2.7V \le V_{CC} \le 5.5V$	$I_{OH} = -0.4 \text{ mA}$	2.4			

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.





Table 4. AC Characteristics

Applicable over recommended operating range from $T_A = -40^{\circ}\text{C}$ to + 125°C, $V_{CC} = \text{As Specified}$, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Тур	Max	Units
f _{SK}	SK Clock Frequency	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		0 0		2 1	MHz
t _{SKH}	SK High Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t _{SKL}	SK Low Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t _{CS}	Minimum CS Low Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t _{CSS}	CS Setup Time	Relative to SK	$\begin{array}{c} 4.5 V \leq V_{CC} \leq 5.5 V \\ 2.7 V \leq V_{CC} \leq 5.5 V \end{array}$	50 50			ns
t _{DIS}	DI Setup Time	Relative to SK	$\begin{array}{c} 4.5 V \leq V_{CC} \leq 5.5 V \\ 2.7 V \leq V_{CC} \leq 5.5 V \end{array}$	100 100			ns
t _{CSH}	CS Hold Time	Relative to SK		0			ns
t _{DIH}	DI Hold Time	Relative to SK	$\begin{array}{c} 4.5V \leq V_{CC} \leq 5.5V \\ 2.7V \leq V_{CC} \leq 5.5V \end{array}$	100 100			ns
t _{PD1}	Output Delay to "1"	AC Test	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			250 500	ns
t _{PD0}	Output Delay to "0"	AC Test	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			250 500	ns
t _{SV}	CS to Status Valid	AC Test	$\begin{array}{c} 4.5 V \leq V_{CC} \leq 5.5 V \\ 2.7 V \leq V_{CC} \leq 5.5 V \end{array}$			250 250	ns
t _{DF}	CS to DO in High Impedance	AC Test CS = V _{IL}	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			100 150	ns
t _{WP}	Write Cycle Time		$2.7V \le V_{CC} \le 5.5V$	0.1	3	10	ms
Endurance ⁽¹⁾	5.0V, 25°C			1M			Write Cycles

Note: 1. This parameter is characterized and is not 100% tested.

Functional Description

The AT93C46A is accessed via a simple and versatile three-wire serial communication interface. Device operation is controlled by seven instructions issued by the host processor. A valid instruction starts with a rising edge of CS and consists of a start bit (logic "1") followed by the appropriate op code and the desired memory address location.

Table 5. Instruction Set for the AT93C46A

			Address	
Instruction	SB	Op Code	x 16	Comments
READ	1	10	$A_5 - A_0$	Reads data stored in memory, at specified address.
EWEN	1	00	11XXXX	Write enable must precede all programming modes.
ERASE	1	11	$A_5 - A_0$	Erase memory location A _n – A ₀ .
WRITE	1	01	$A_5 - A_0$	Writes memory location $A_n - A_0$.
ERAL	1	00	10XXXX	Erases all memory locations. Valid only at $V_{\rm CC}$ = 4.5V to 5.5V.
WRAL	1	00	01XXXX	Writes all memory locations. Valid only at $V_{CC} = 4.5V$ to 5.5V.
EWDS	1	00	00XXXX	Disables all programming instructions.

READ (READ): The Read (READ) instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory location is available at the serial output pin DO. Output data changes are synchronized with the rising edges of serial clock SK. It should be noted that a dummy bit (logic "0") precedes the 16-bit data output string.

ERASE/WRITE ENABLE (EWEN): To assure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out. Please note that once in the EWEN state, programming remains enabled until an EWDS instruction is executed or V_{CC} power is removed from the part.

ERASE (ERASE): The Erase (ERASE) instruction programs all bits in the specified memory location to the logical "1" state. The self-timed erase cycle starts once the Erase instruction and address are decoded. The DO pin outputs the ready/busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). A logic "1" at pin DO indicates that the selected memory location has been erased and the part is ready for another instruction.

WRITE (WRITE): The Write (WRITE) instruction contains the 16 bits of data to be written into the specified memory location. The self-timed programming cycle, t_{WP} , starts after the last bit of data is received at serial data input pin DI. The DO pin outputs the ready/busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). A logic "0" at DO indicates that programming is still in progress. A logic "1" indicates that the memory location at the specified address has been written with the data pattern contained in the instruction and the part is ready for further instructions. A ready/busy status cannot be obtained if the CS is brought high after the end of the self-timed programming cycle, t_{WP}

ERASE ALL (ERAL): The Erase All (ERAL) instruction programs every bit in the memory array to the logic "1" state and is primarily used for testing purposes. The DO pin outputs the READY/BUSY status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). The ERAL instruction is valid only at $V_{CC} = 5.0V \pm 10\%$.

WRITE ALL (WRAL): The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the READY/BUSY



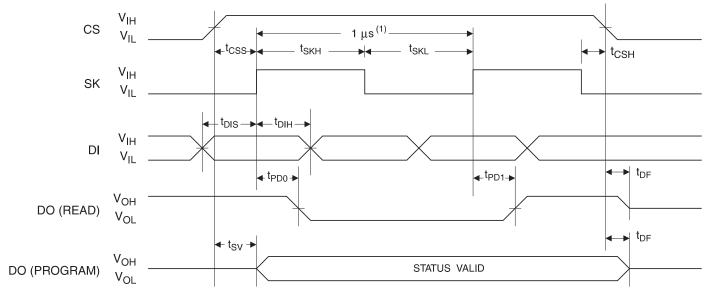


status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). The WRAL instruction is valid only at V_{CC} = 5.0V \pm 10%.

ERASE/WRITE DISABLE (EWDS): To protect against accidental data disturb, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the READ instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.

Timing Diagrams

Figure 2. Synchronous Data Timing



Note: 1. This is the minimum SK period.

Table 6. Organization Key for Timing Diagrams

	AT93C46A
I/O	x 16
A_N	A_5
D_N	D ₁₅

Figure 3. READ Timing

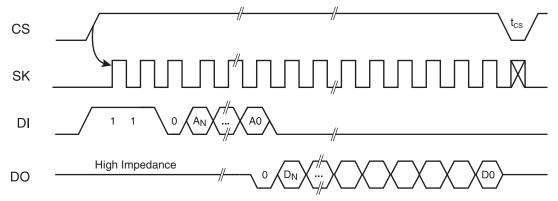
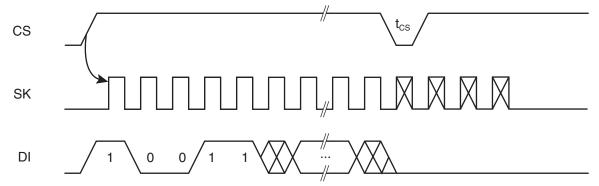
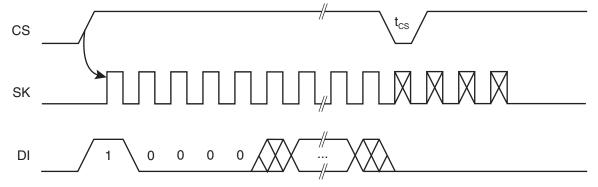


Figure 4. EWEN Timing⁽¹⁾



Note: 1. Requires a minimum of nine clock cycles.

Figure 5. EWDS Timing⁽¹⁾



Note: 1. Requires a minimum of nine clock cycles.



Figure 6. WRITE Timing

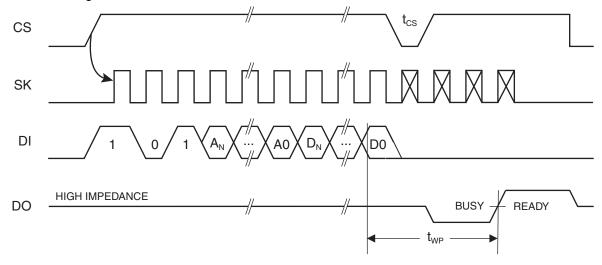
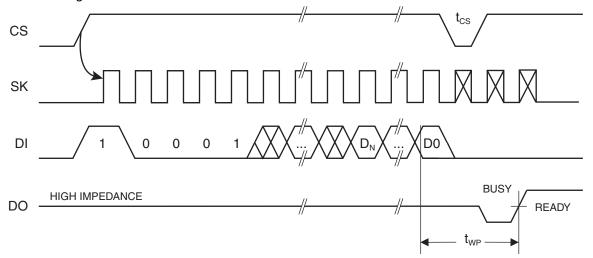


Figure 7. WRAL Timing^(1,2)



Notes: 1. Valid only at $V_{CC} = 4.5V$ to 5.5V. 2. Requires a minimum of nine clock cycles.

Figure 8. ERASE Timing

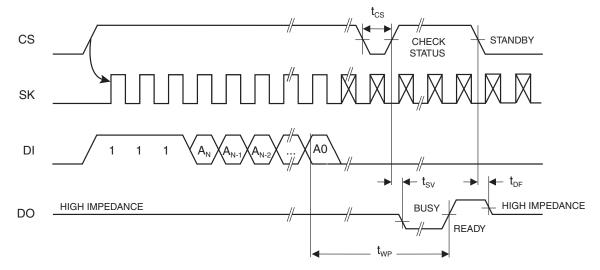
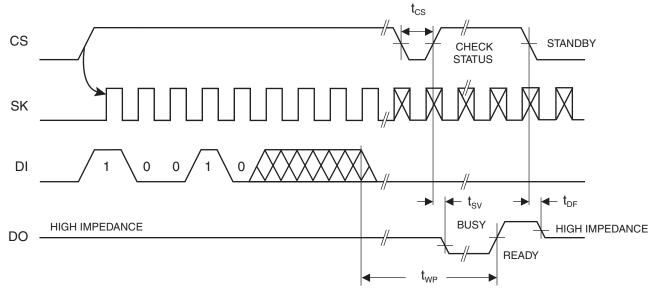


Figure 9. ERAL Timing⁽¹⁾



Note: 1. Valid only at $V_{CC} = 4.5V$ to 5.5V.



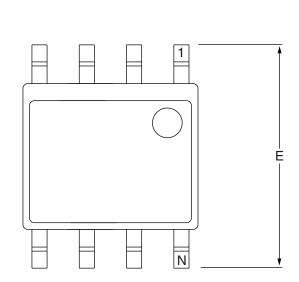
Ordering Information

Ordering Code	Package	Operation Range
AT93C46A-10SQ-2.7 AT93C46A-10TQ-2.7	8S1 8A2	Lead-free/Halogen-free/ Extended Temperature (-40°C to 125°C)

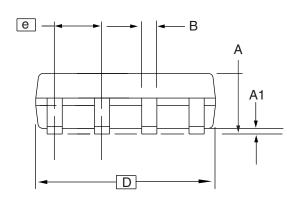
	Package Type				
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)				
8A2	8-lead, 0.170" Wide, Thin Shrink Small Outline Package (TSSOP)				
	Options				
-2.7	Low Voltage (2.7V to 5.5V)				

Packaging Information

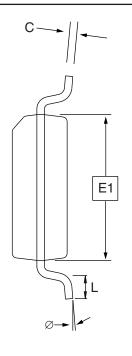
8S1 - JEDEC SOIC



Top View



Side View



End View

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	1.35	_	1.75	
A1	0.10	_	0.25	
b	0.31	_	0.51	
С	0.17	_	0.25	
D	4.80	_	5.00	
E1	3.81	_	3.99	
E	5.79	_	6.20	
е	1.27 BSC			
L	0.40	_	1.27	
Ø	0°	_	8°	

Note: These drawings are for general information only. Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.

10/7/03

В



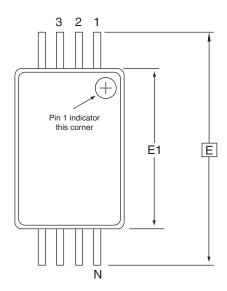
1150 E. Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 8S1, 8-lead (0.150" Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)

REV. DRAWING NO. 8S1

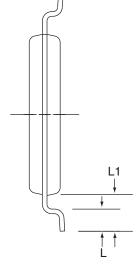




8A2 -TSSOP



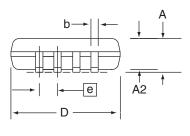
Top View



End View

COMMON DIMENSIONS

(Unit of Measure = mm)



Side View

SYMBOL	MIN	NOM	MAX	NOTE
D	2.90	3.00	3.10	2, 5
E		6.40 BSC		
E1	4.30	4.40	4.50	3, 5
Α	_	_	1.20	
A2	0.80	1.00	1.05	
b	0.19	_	0.30	4
е				
L	0.45	0.60	0.75	
L1		1.00 REF		

Notes: 1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.

- 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15 mm (0.006 in) per side.
- 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25 mm (0.010 in) per side.
- 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07 mm.
- 5. Dimension D and E1 to be determined at Datum Plane H.

5/30/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	8A2, 8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)	8A2	В

Revision History

Doc. Rev.	Date	Comments
5089B	1/2007	Implemented revision history
		Removed PDIP package offering
		Removed Pb'd parts





Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311

Fax: 1(408) 487-2600

Regional Headquarters

Europe

Atmel Sarl Route des Arsenaux 41 Case Postale 80 CH-1705 Fribourg Switzerland

Tel: (41) 26-426-5555 Fax: (41) 26-426-5500

Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon Hong Kong

Tel: (852) 2721-9778 Fax: (852) 2722-1369

Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan

Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Atmel Operations

Memory

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

Microcontrollers

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

La Chantrerie BP 70602 44306 Nantes Cedex 3, France Tel: (33) 2-40-18-18-18 Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards

Zone Industrielle 13106 Rousset Cedex, France Tel: (33) 4-42-53-60-00

Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA

Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Scottish Enterprise Technology Park Maxwell Building East Kilbride G75 0QR, Scotland

Tel: (44) 1355-803-000 Fax: (44) 1355-242-743

RF/Automotive

Theresienstrasse 2 Postfach 3535 74025 Heilbronn, Germany Tel: (49) 71-31-67-0 Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA

Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/ High Speed Converters/RF Datacom

Avenue de Rochepleine BP 123

38521 Saint-Egreve Cedex, France

Tel: (33) 4-76-58-30-00 Fax: (33) 4-76-58-34-80

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